

FULL ADDITIVE PROCESS WITH FILLED PLATED THROUGH HOLES

ABSTRACT

A method provides for additive plating on a subcomposite having filled plated through holes. Fine-line circuitry is achieved via electroless deposition onto a dielectric substrate after the through hole is plated and filled. Fine-line circuitry may be routed over landless, plated through holes thereby increasing the aspect ratio and the available surface area for additional components and wiring.

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